

# N-Channel 20 V (D-S) MOSFET



| PRODUCT SUMMARY  |        |  |  |  |  |
|--|--------|--|--|--|--|
| V <sub>DS</sub> (V)  | 20     |  |  |  |  |
| $R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 10 \text{ V}$  | 0.0026 |  |  |  |  |
| $R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 4.5 \text{ V}$ | 0.0032 |  |  |  |  |
| Q <sub>g</sub> typ. (nC)                                   | 28.7   |  |  |  |  |
| I <sub>D</sub> (A) <sup>a</sup>                            | 35.8   |  |  |  |  |
| Configuration  | Single |  |  |  |  |

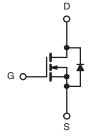
#### **FEATURES**

- TrenchFET® power MOSFET
- 100 % R<sub>g</sub> and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



#### **APPLICATIONS**

- OR-ing
- DC/DC low-side switch



N-Channel MOSFET

| ORDERING INFORMATION            |                 |  |  |  |
|---------------------------------|-----------------|--|--|--|
| Package                         | SO-8            |  |  |  |
| Lead (Pb)-free and halogen-free | Si4186DY-T1-GE3 |  |  |  |

| PARAMETER  Drain-source voltage  Gate-source voltage |                        | SYMBOL                            | LIMIT                |     |
|--|------------------------|-----------------------------------|----------------------|-----|
|  |                        | V <sub>DS</sub>                   | 20                   |     |
|  |                        | V <sub>GS</sub>                   | ± 20                 |     |
|  | T <sub>C</sub> = 25 °C |                                   | 35.8                 |     |
| Continuous drain current (T <sub>J</sub> = 150 °C)   | T <sub>C</sub> = 70 °C | 1 . [                             | 26.5                 |     |
|  | T <sub>A</sub> = 25 °C |                                   | 25.3 <sup>b, c</sup> |     |
|  | T <sub>A</sub> = 70 °C | 1                                 | 20.1 <sup>b, c</sup> |     |
| Pulsed drain current                                 |                        | I <sub>DM</sub>                   | 70                   | Α   |
| On the second second second                          | T <sub>C</sub> = 25 °C |                                   | 5.4                  |     |
| Continuous source-drain diode current                | T <sub>A</sub> = 25 °C | ls –                              | 2.7 b, c             |     |
| Single pulse avalanche current                       |                        | I <sub>AS</sub>                   | 30                   |     |
| Avalanche energy                                     | L = 0.1 mH             | E <sub>AS</sub>                   | 45                   | mJ  |
| Maximum power dissipation                            | T <sub>C</sub> = 25 °C |                                   | 6                    |     |
|  | T <sub>C</sub> = 70 °C | 1 , [                             | 3.3                  | 147 |
|  | T <sub>A</sub> = 25 °C | P <sub>D</sub>                    | 3 b, c               | W   |
|  | T <sub>A</sub> = 70 °C | 1                                 | 1.9 <sup>b, c</sup>  |     |
| Operating junction and storage temperature range     |                        | T <sub>J</sub> , T <sub>stg</sub> | -55 to +150          | °C  |

| THERMAL RESISTANCE RATINGS       |              |                   |         |      |      |  |  |
|----------------------------------|--------------|-------------------|---------|------|------|--|--|
| PARAMETER                        | SYMBOL       | TYPICAL           | MAXIMUM | UNIT |      |  |  |
| Maximum junction-to-ambient b, d | t ≤ 10 s     | R <sub>thJA</sub> | 33      | 42   | °C/W |  |  |
| Maximum junction-to-foot (drain) | Steady state | R <sub>thJF</sub> | 16      | 21   | C/W  |  |  |

#### Notes

- a. Based on  $T_C = 25$  °C
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 10 s
- d. Maximum under steady state conditions is 85 °C/W



# Vishay Siliconix

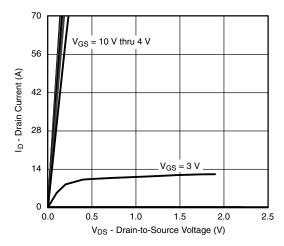
| PARAMETER   | SYMBOL                  | TEST CONDITIONS   | MIN. | TYP.   | MAX.   | UNIT    |  |
|---|-------------------------|---|------|--------|--------|---------|--|
| Static  |                         |   |      |        |        |         |  |
| Drain-source breakdown voltage  | V <sub>DS</sub>         | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$                         | 20   | -      | -      | V       |  |
| V <sub>DS</sub> temperature coefficient   | $\Delta V_{DS}/T_{J}$   | J 050 ··· A   | -    | 20     | -      | \//90   |  |
| V <sub>GS(th)</sub> temperature coefficient   | $\Delta V_{GS(th)}/T_J$ | $I_D = 250 \mu A$   | -    | -6.7   | -      | mV/°C   |  |
| Gate-source threshold voltage   | V <sub>GS(th)</sub>     | $V_{DS} = V_{GS}$ , $I_D = 250 \mu A$                                 | 1.2  | -      | 2.4    | V       |  |
| Gate-source leakage   | I <sub>GSS</sub>        | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$                     | -    | -      | ± 100  | nA      |  |
| Zero gate voltage drain current   |                         | $V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$                         | -    | -      | 1      | μА      |  |
|   | I <sub>DSS</sub>        | V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C | -    | -      | 10     |         |  |
| On-state drain current <sup>a</sup>   | I <sub>D(on)</sub>      | $V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$                       | 30   | -      | -      | Α       |  |
| During a second of the second | Б                       | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A                         | -    | 0.0021 | 0.0026 | Ω       |  |
| Drain-source on-state resistance a  | R <sub>DS(on)</sub>     | $V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$                          | -    | 0.0026 | 0.0032 |         |  |
| Forward transconductance <sup>a</sup>   | 9 <sub>fs</sub>         | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 15 A                         | -    | 63     | -      | S       |  |
| Dynamic <sup>b</sup>  |                         |   |      |        |        |         |  |
| Input capacitance   | C <sub>iss</sub>        |   | -    | 3630   | -      |         |  |
| Output capacitance  | C <sub>oss</sub>        | $V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$      | -    | 1085   | -      | pF      |  |
| Reverse transfer capacitance  | C <sub>rss</sub>        |   | -    | 453    | -      |         |  |
|   | Q <sub>g</sub>          | V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A | -    | 60     | 90     | nC      |  |
| Total gate charge   |                         |   | -    | 28.7   | 44     |         |  |
| Gate-source charge  | Q <sub>qs</sub>         | $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$ | -    | 8.9    | -      |         |  |
| Gate-drain charge   | Q <sub>qd</sub>         |   | -    | 7.4    | -      |         |  |
| Gate resistance   | $R_g$                   | f = 1 MHz   | 0.3  | 1.2    | 2.4    | Ω       |  |
| Turn-on delay time  | t <sub>d(on)</sub>      |   | -    | 29     | 55     |         |  |
| Rise time   | t <sub>r</sub>          | $V_{DD} = 10 \text{ V}, R_{I} = 1 \Omega,$                            | -    | 16     | 30     | 1       |  |
| Turn-off delay time   | t <sub>d(off)</sub>     | $I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$     | -    | 40     | 75     |         |  |
| Fall time   | t <sub>f</sub>          |   | -    | 13     | 26     |         |  |
| Turn-on delay time  | t <sub>d(on)</sub>      |   | -    | 12     | 24     | ns<br>- |  |
| Rise time   | t <sub>r</sub>          | $V_{DD} = 10 \text{ V}, R_{L} = 1 \Omega,$                            | -    | 9      | 18     |         |  |
| Turn-off delay time   | t <sub>d(off)</sub>     | $I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$      | -    | 32     | 60     |         |  |
| Fall time   | t <sub>f</sub>          |   | -    | 9      | 18     |         |  |
| <b>Drain-Source Body Diode Characterist</b>   | ics                     |   |      |        |        |         |  |
| Continuous source-drain diode current   | I <sub>S</sub>          | T <sub>C</sub> = 25 °C  | -    | -      | 5.4    |         |  |
| Pulse diode forward current <sup>a</sup>  | I <sub>SM</sub>         |   | -    | -      | 70     | Α       |  |
| Body diode voltage  | V <sub>SD</sub>         | I <sub>S</sub> = 4 A  | -    | 0.74   | 1.1    | V       |  |
| Body diode reverse recovery time  | t <sub>rr</sub>         |   | -    | 30     | 60     | ns      |  |
| Body diode reverse recovery charge  | Q <sub>rr</sub>         | $I_F = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$      | -    | 20     | 40     | nC      |  |
| Reverse recovery fall time  | t <sub>a</sub>          | T <sub>J</sub> = 25 °C  | -    | 16     | -      |         |  |
| Reverse recovery rise time  | t <sub>b</sub>          |   | -    | 14     | -      | ns      |  |

#### **Notes**

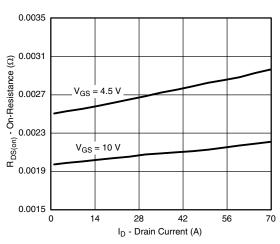
- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

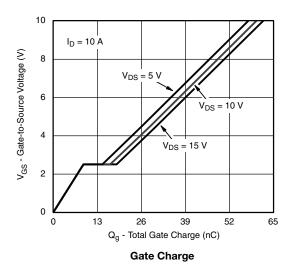


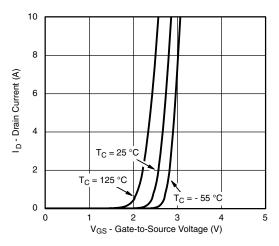


#### **Output Characteristics**

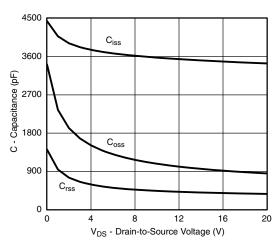


On-Resistance vs. Drain Current and Gate Voltage

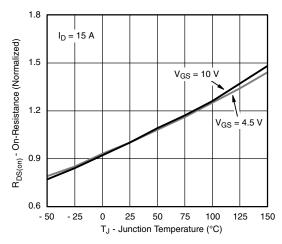




**Transfer Characteristics** 

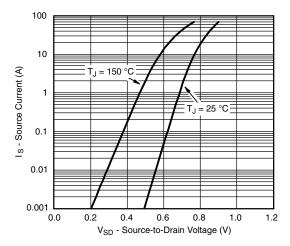


Capacitance

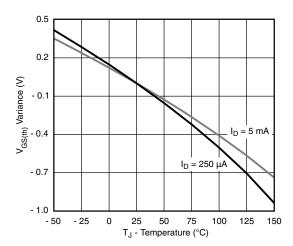


On-Resistance vs. Junction Temperature

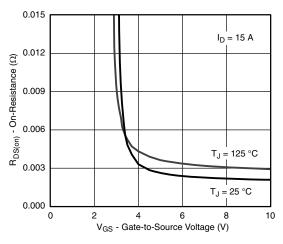




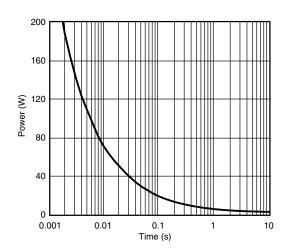
#### Source-Drain Diode Forward Voltage



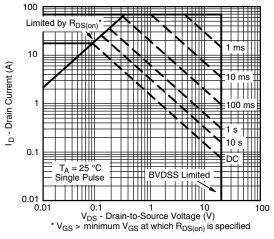
**Threshold Voltage** 



On-Resistance vs. Gate-to-Source Voltage

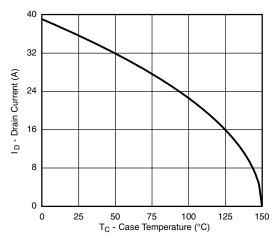


Single Pulse Power, Junction-to-Ambient

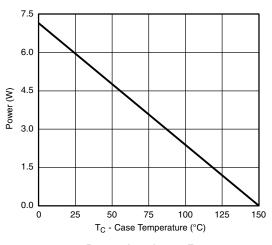


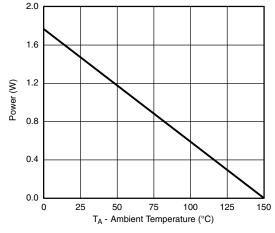
Safe Operating Area, Junction-to-Ambient





#### Current Derating a





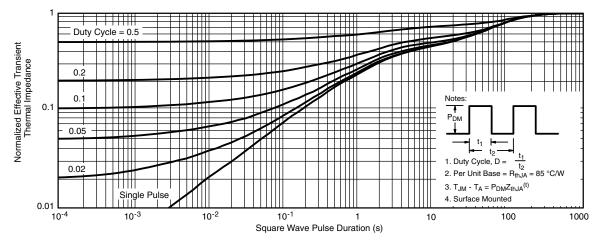
Power, Junction-to-Foot

Power, Junction-to-Ambient

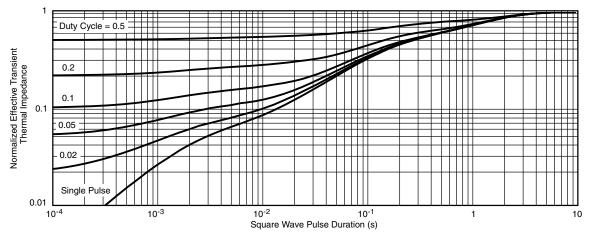
#### Note

a. The power dissipation P<sub>D</sub> is based on T<sub>J</sub> max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient



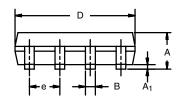
Normalized Thermal Transient Impedance, Junction-to-Foot

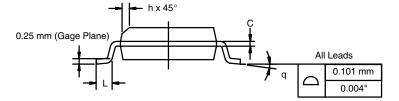
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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







|                                | MILLIM | IETERS | INC       | HES   |  |  |
|--------------------------------|--------|--------|-----------|-------|--|--|
| DIM                            | Min    | Max    | Min       | Max   |  |  |
| Α                              | 1.35   | 1.75   | 0.053     | 0.069 |  |  |
| A <sub>1</sub>                 | 0.10   | 0.20   | 0.004     | 0.008 |  |  |
| В                              | 0.35   | 0.51   | 0.014     | 0.020 |  |  |
| С                              | 0.19   | 0.25   | 0.0075    | 0.010 |  |  |
| D                              | 4.80   | 5.00   | 0.189     | 0.196 |  |  |
| Е                              | 3.80   | 4.00   | 0.150     | 0.157 |  |  |
| е                              | 1.27   | BSC    | 0.050 BSC |       |  |  |
| Н                              | 5.80   | 6.20   | 0.228     | 0.244 |  |  |
| h                              | 0.25   | 0.50   | 0.010     | 0.020 |  |  |
| L                              | 0.50   | 0.93   | 0.020     | 0.037 |  |  |
| q                              | 0°     | 8°     | 0°        | 8°    |  |  |
| S                              | 0.44   | 0.64   | 0.018     | 0.026 |  |  |
| ECN: C-06527-Rev. I. 11-Sep-06 |        |        |           |       |  |  |

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06

# APPLICATION NOTE



### **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)

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